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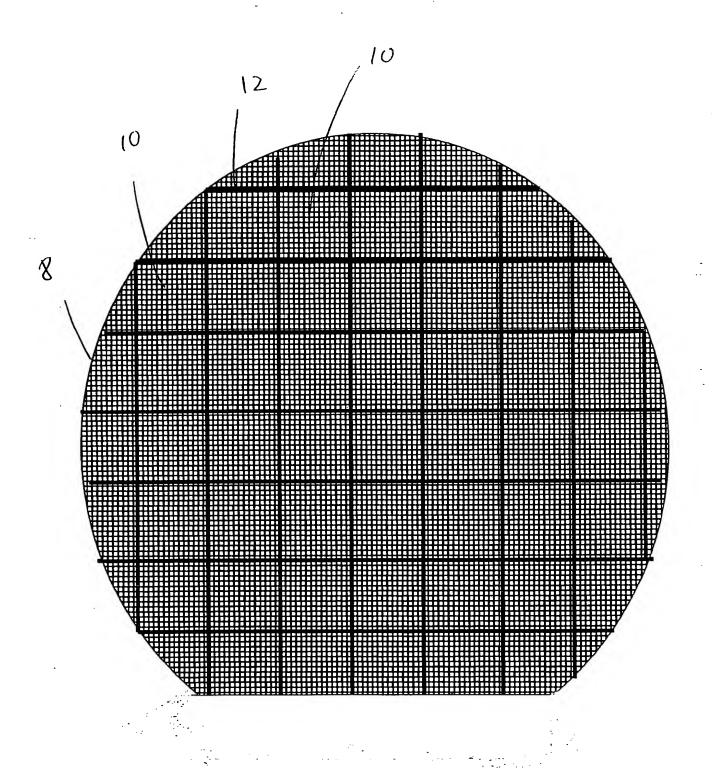


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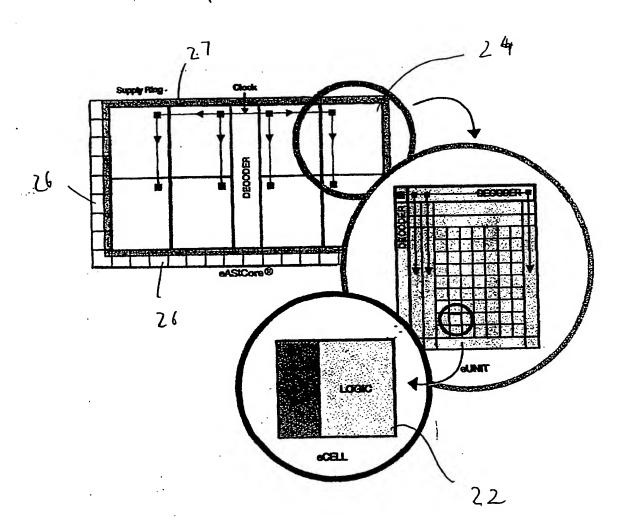


Fig 2

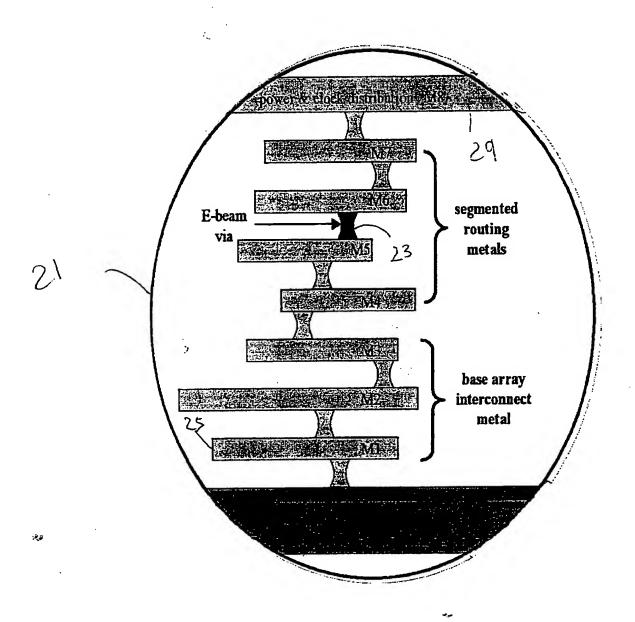


Fig ZA

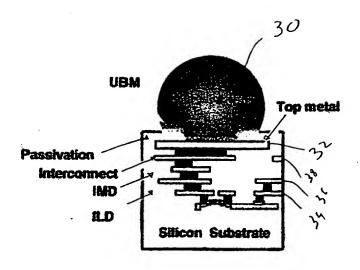


Fig 3 A

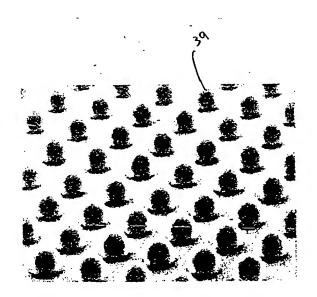
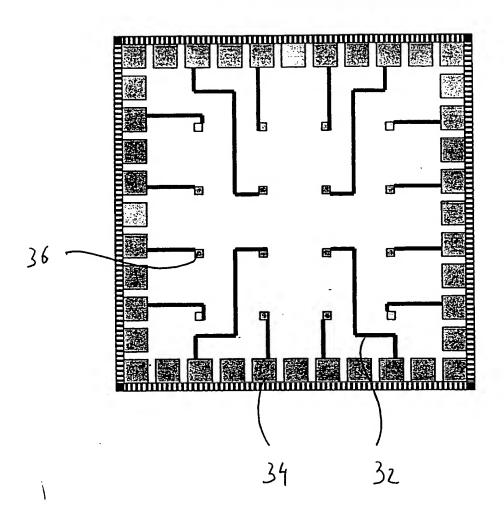


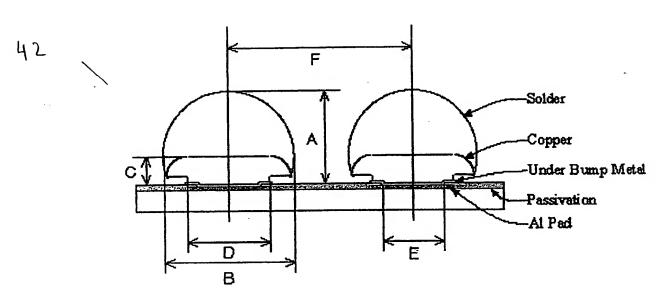
Fig 3B



F: 3 C

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В	Bump Diameter	150μm ±10μm (in Wafer)	70μm ±10μm (in Wafer)
C	Cu Bump Height	20μm ±3μm (in Wafer)	10μm ±3μm (in Wafer)
D	Bump Root Diameter	90μm	60μm
E	Passivation Hole Size	70μm	40μm
F	Bump Pitch	200µm	120μm



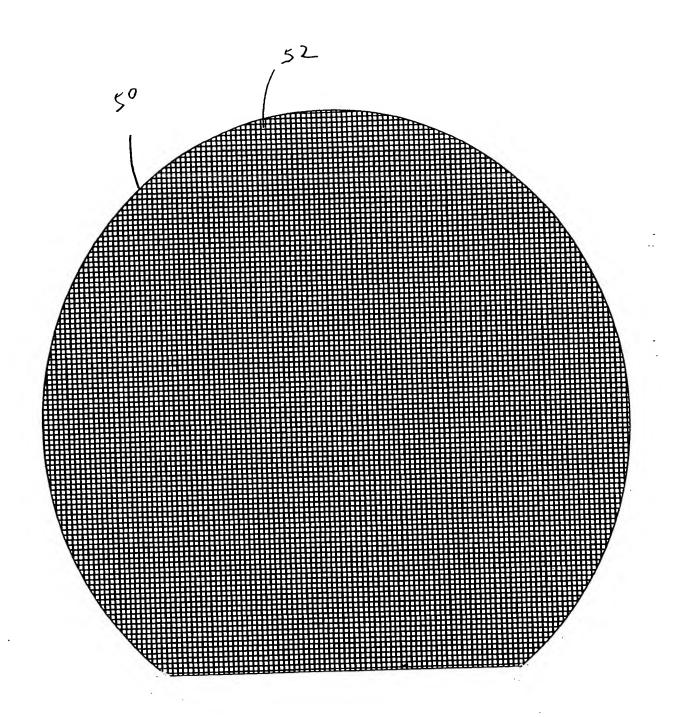


fig 5

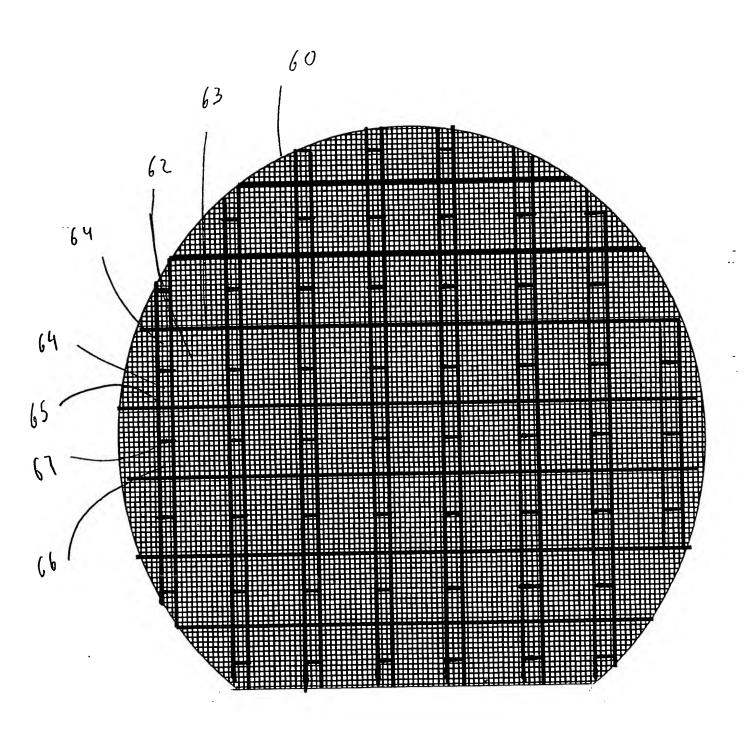


Fig 6

Title: METHOD FOR FABRICATION OF

SEMICONDUCTOR DEVICE Inventor: Zvi OR-BACH et al. Att. Docket No. 38897-199163

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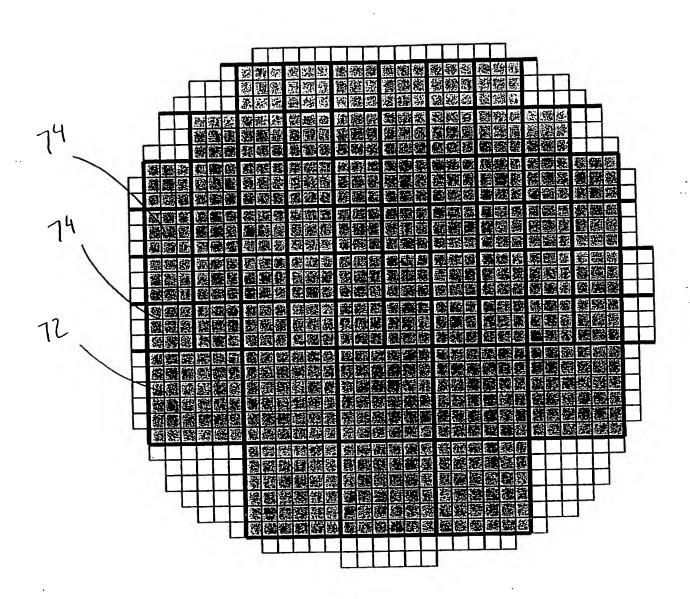
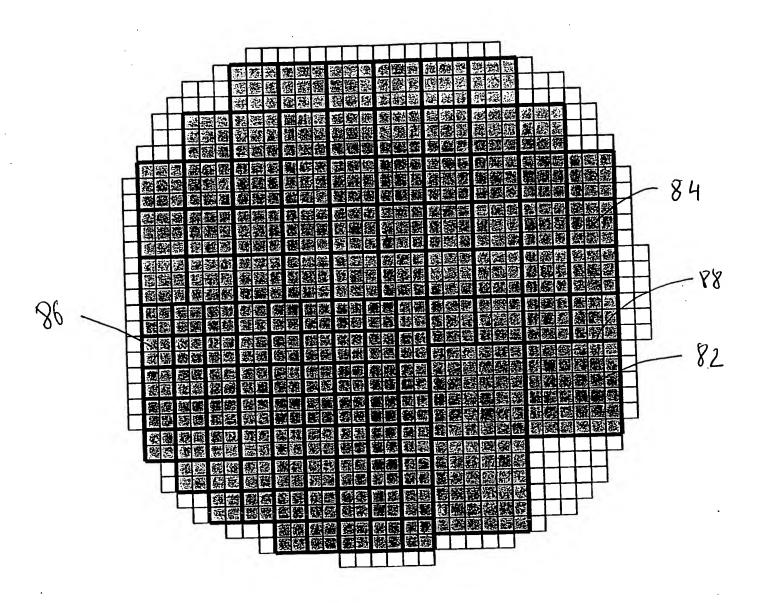


Fig 7

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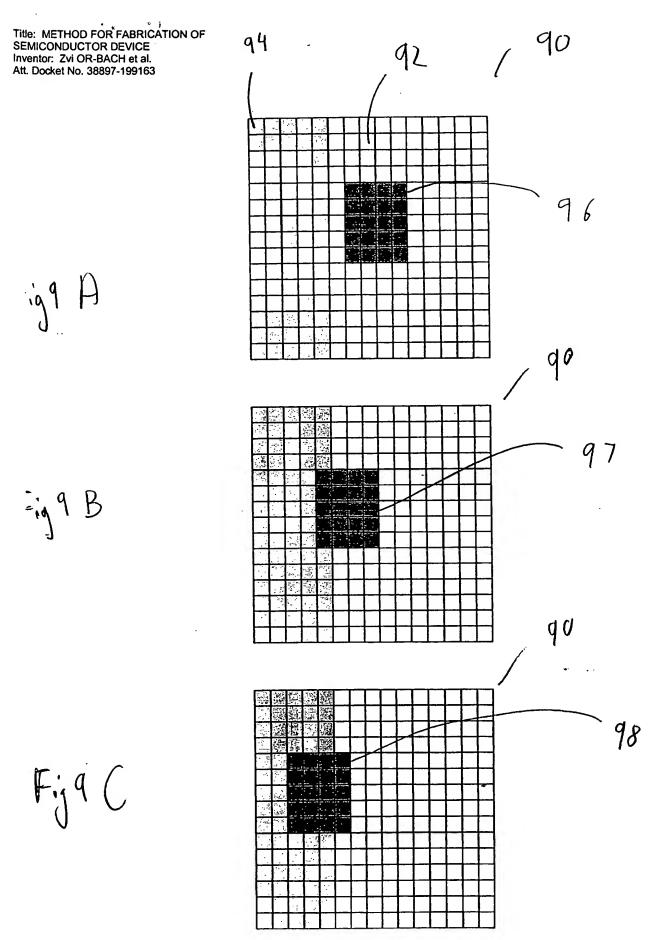
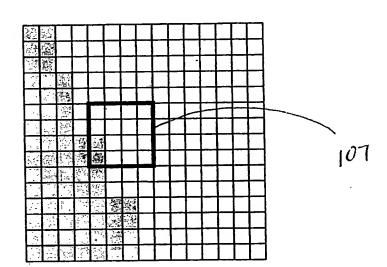


Fig 10 B



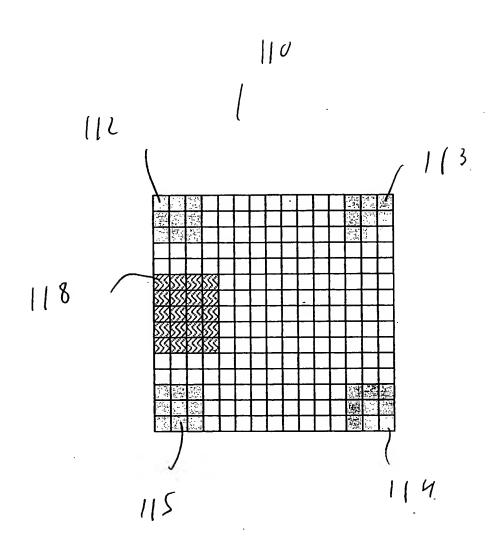
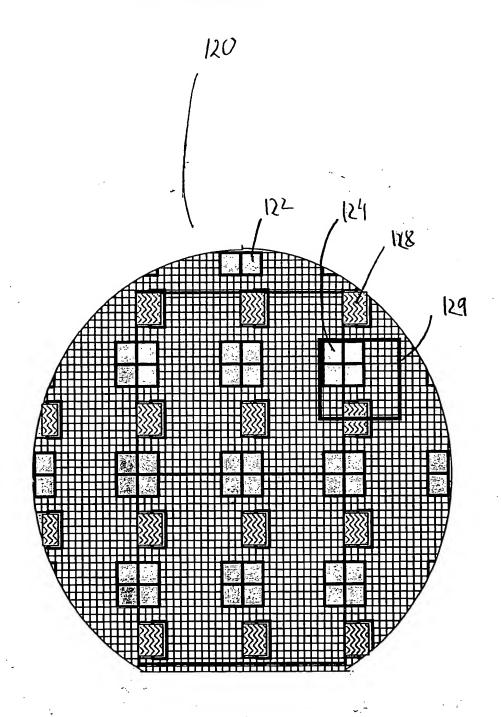


Fig 11



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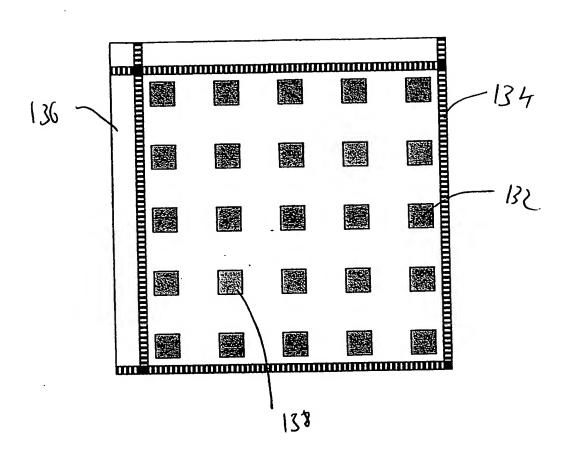
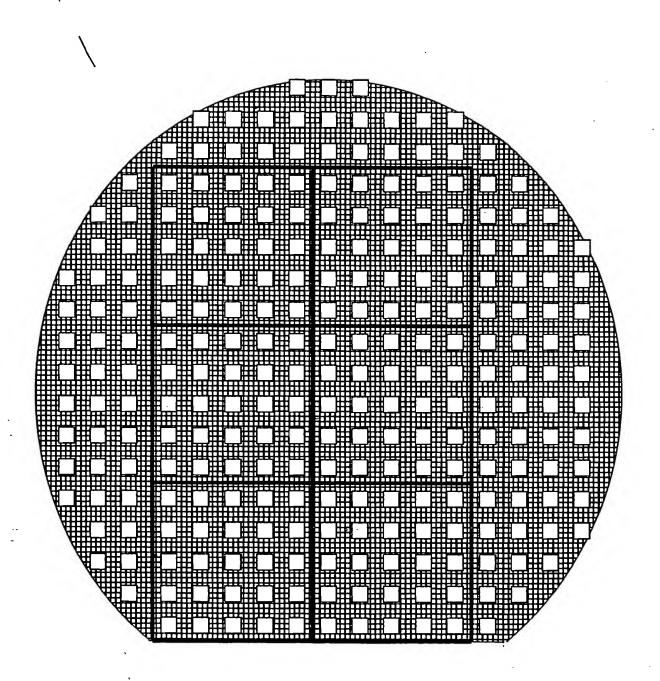


Fig 13

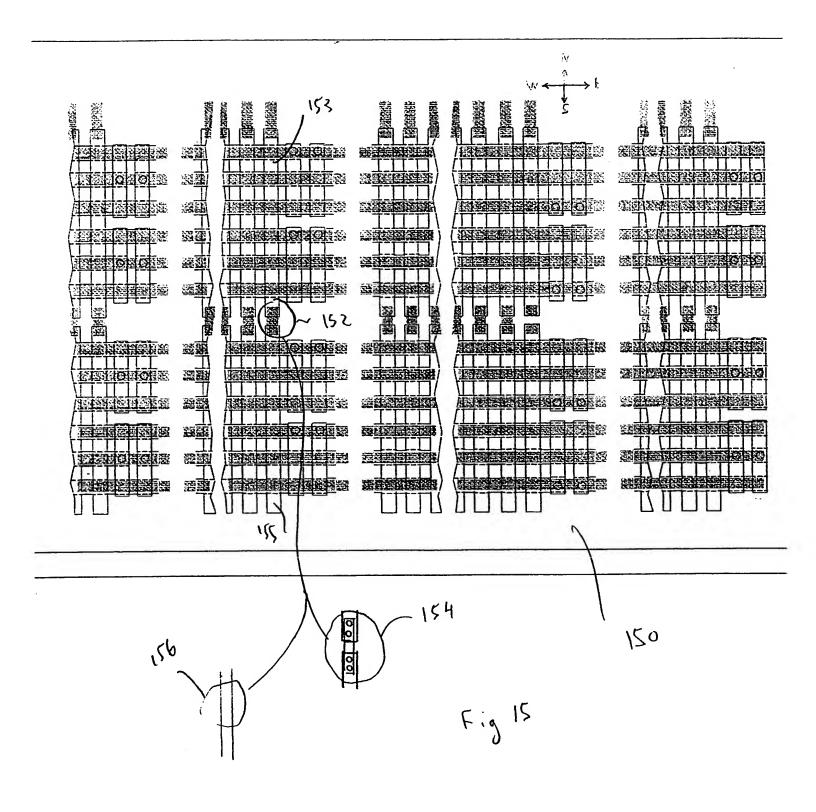
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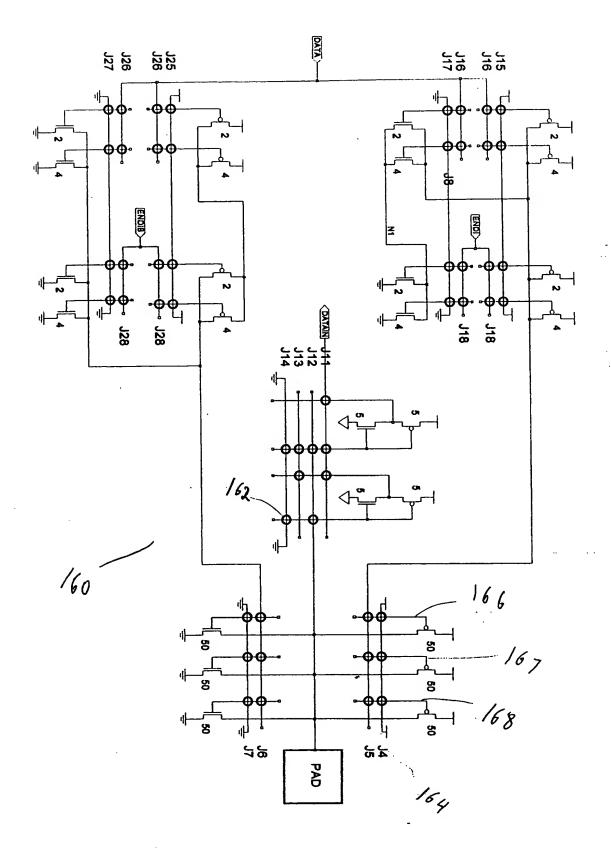


Fig. 16

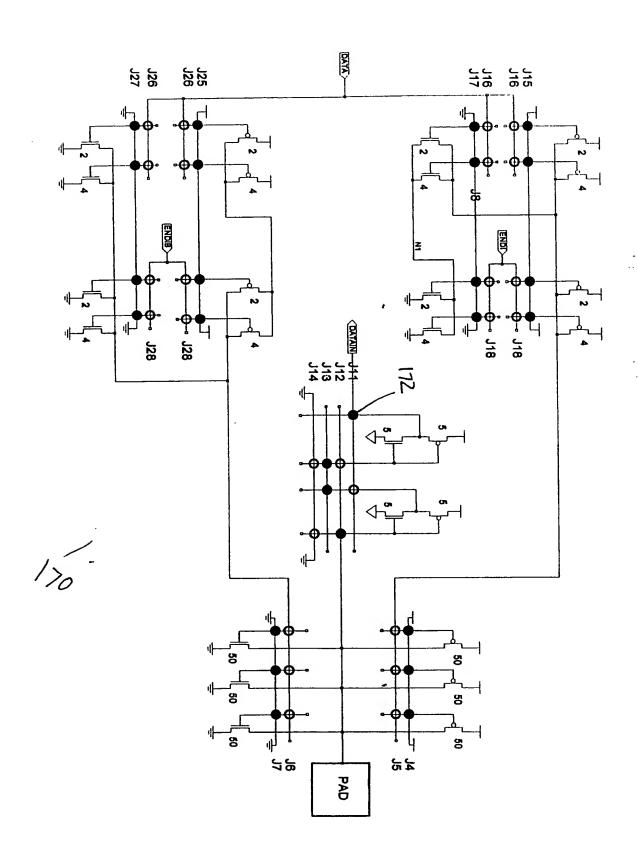


Fig 17

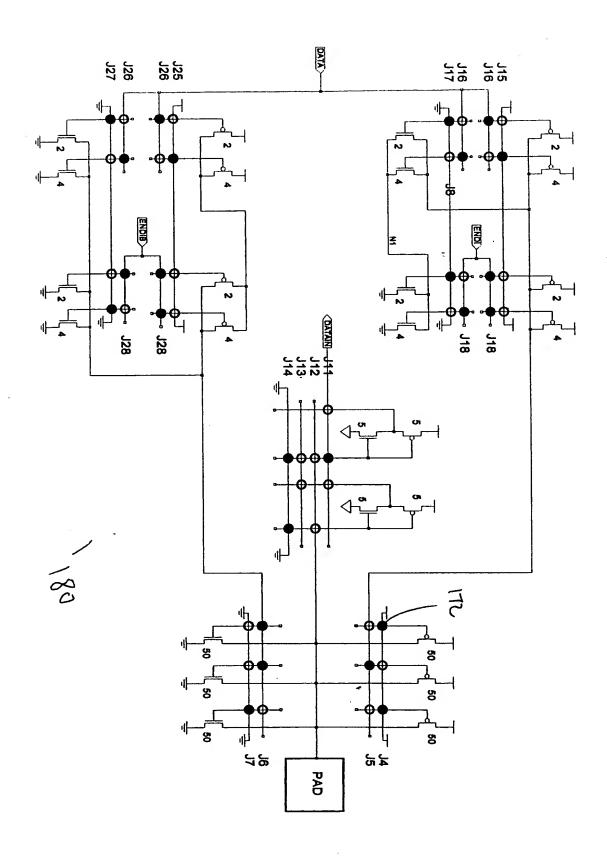


Fig 18

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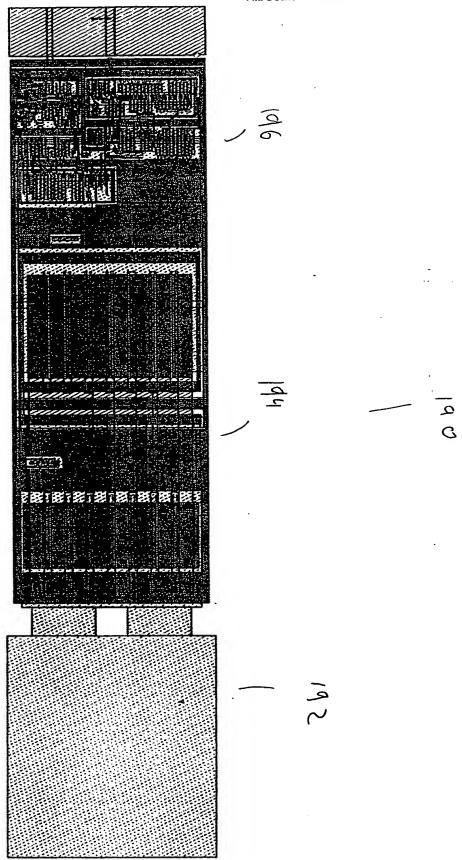


Fig 19

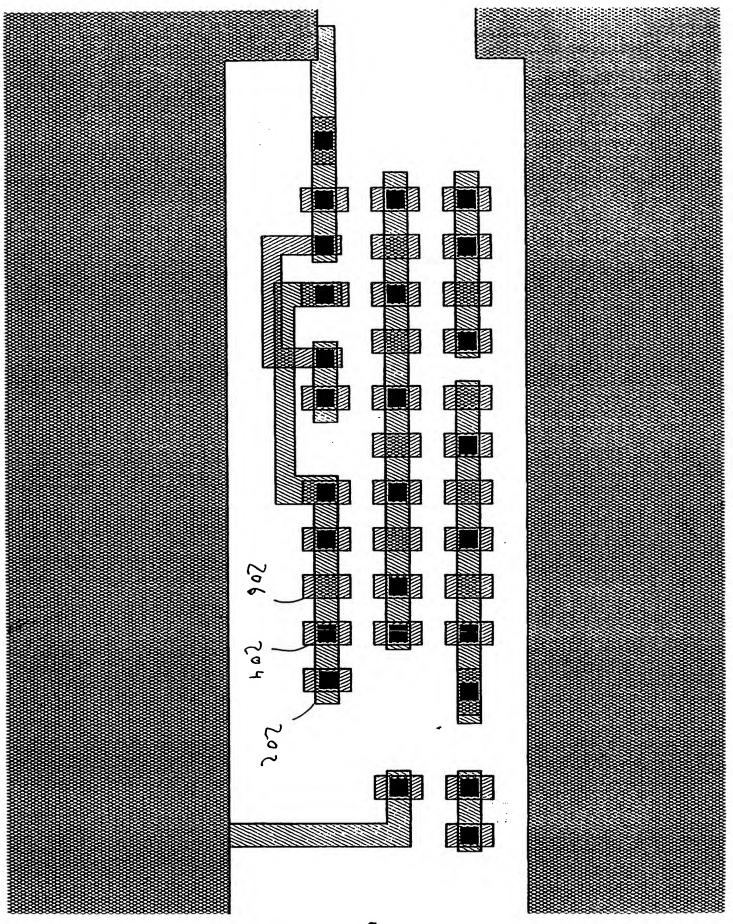


Fig 20

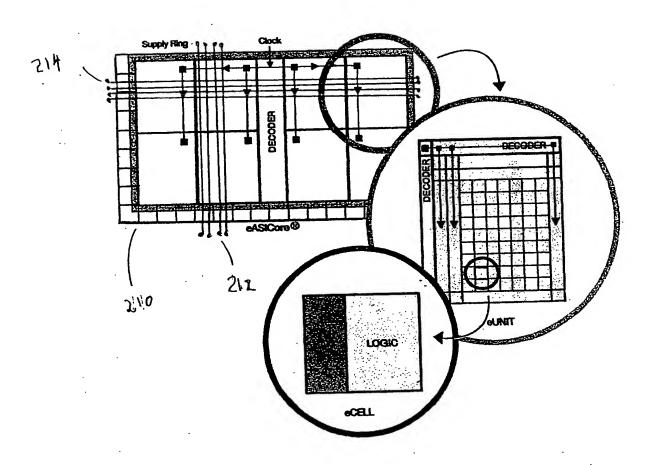


Fig 21

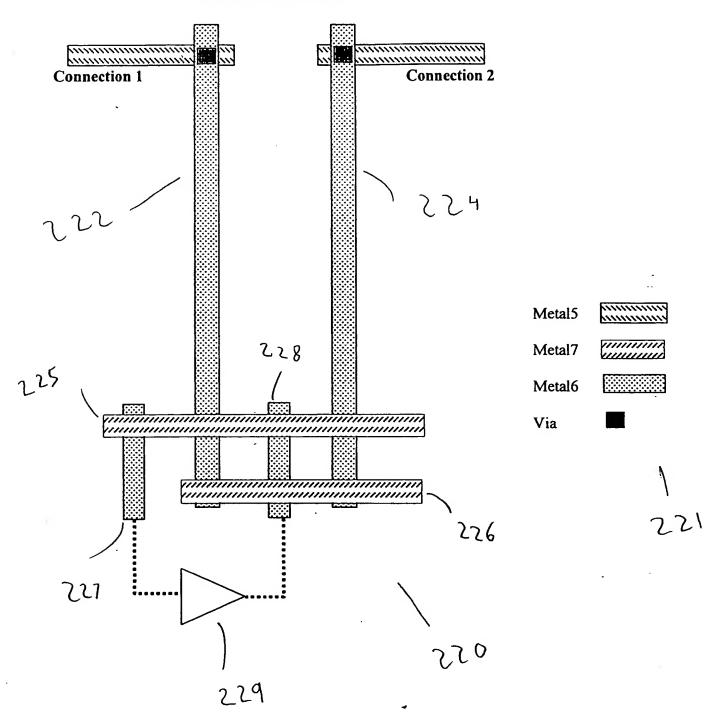


Fig 22

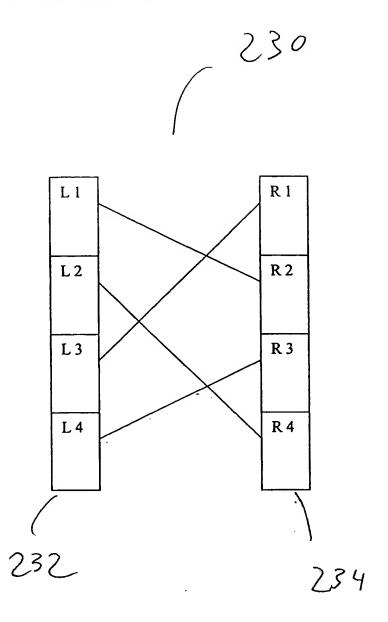
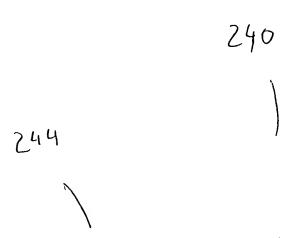


Fig. 23



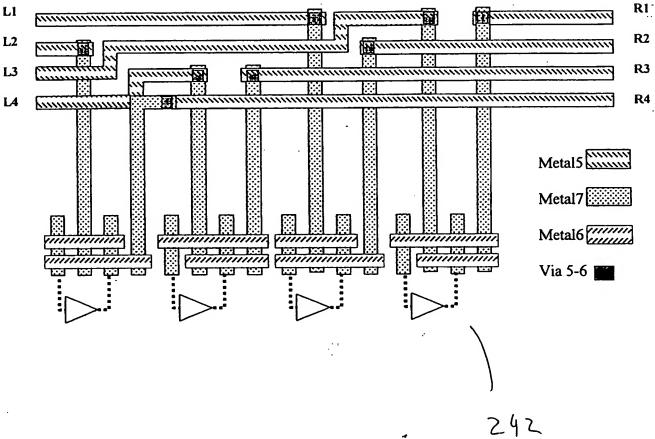
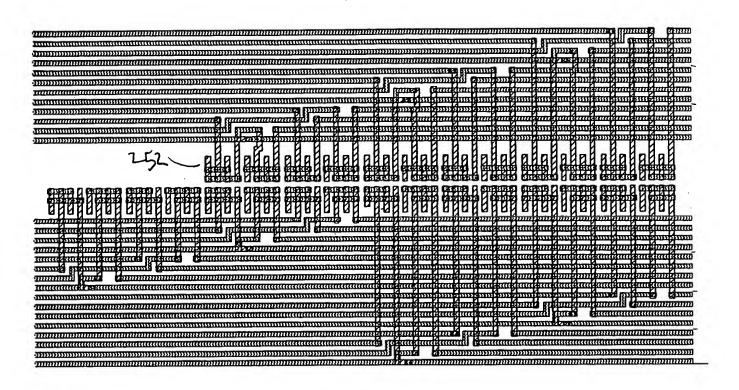


Fig 24

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Fig 25

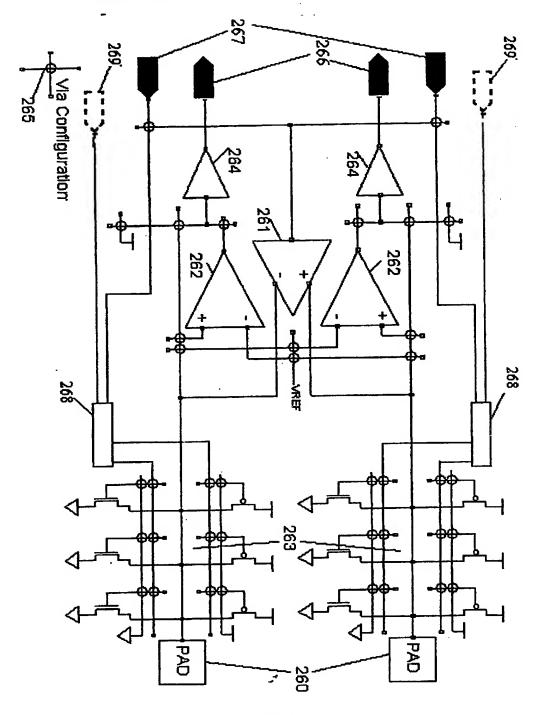


Fig. 26

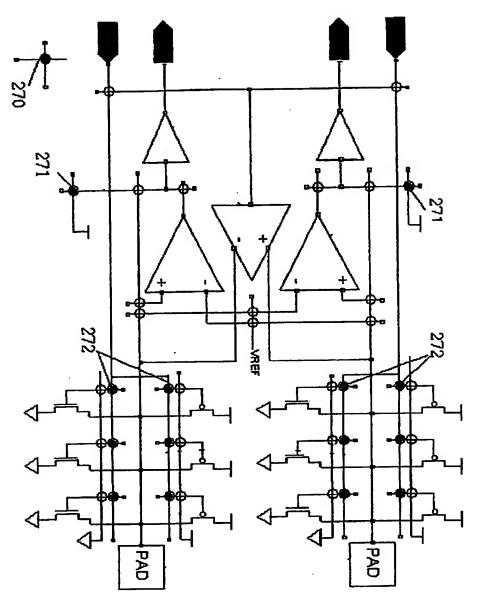


Fig. 27

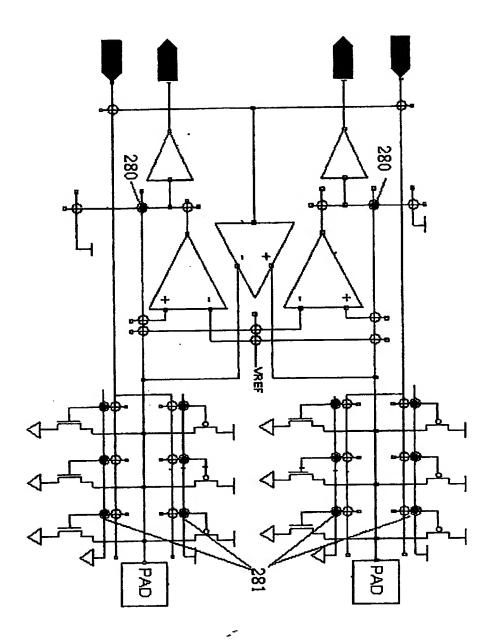


Fig. 28

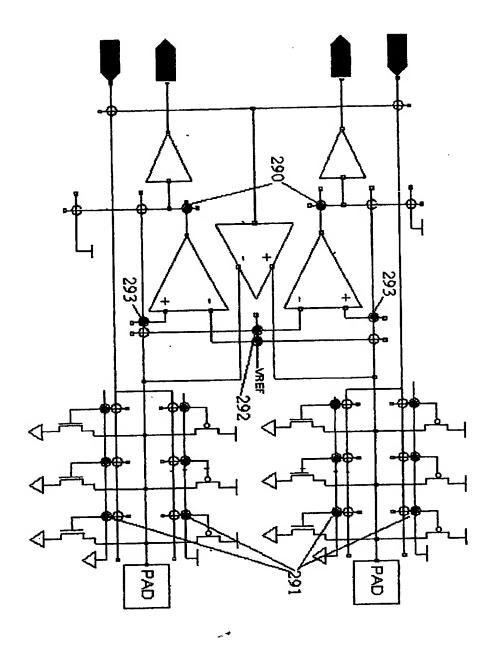


Fig. 29

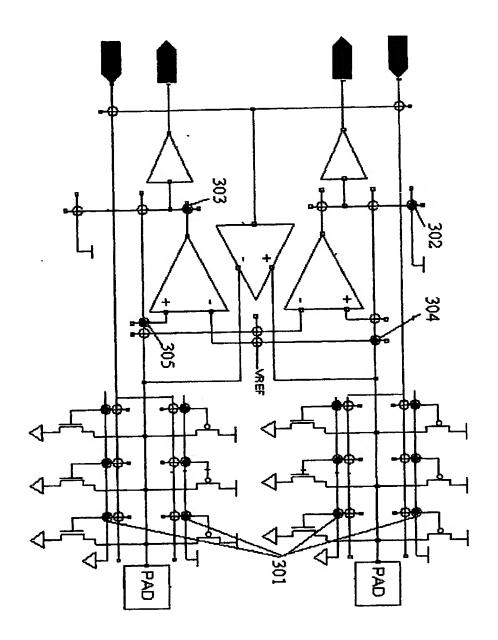


Fig. 30

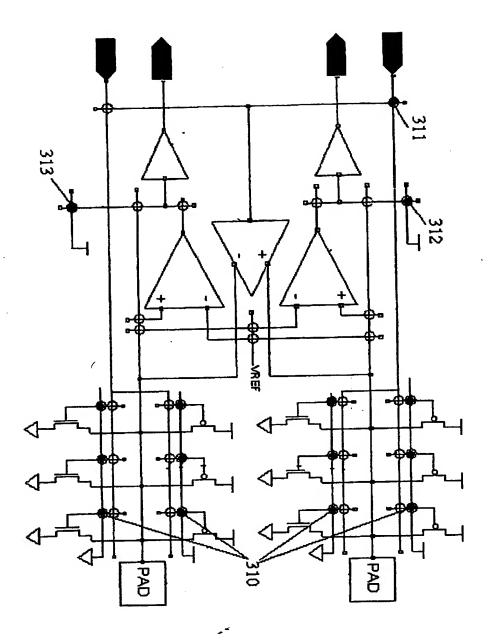


Fig. 31

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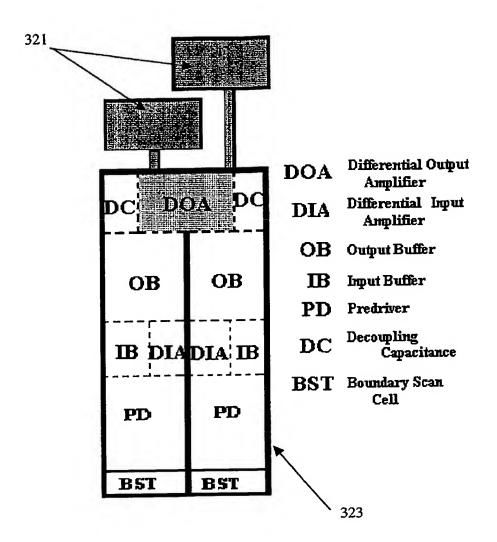


Fig 32

SEMICONDUCTOR DEVICE Inventor: Zvi OR-BACH et al. Att. Docket No. 38897-199163 130 330 338 334 336

Title: METHOD FOR FABRICATION OF

Fig 33

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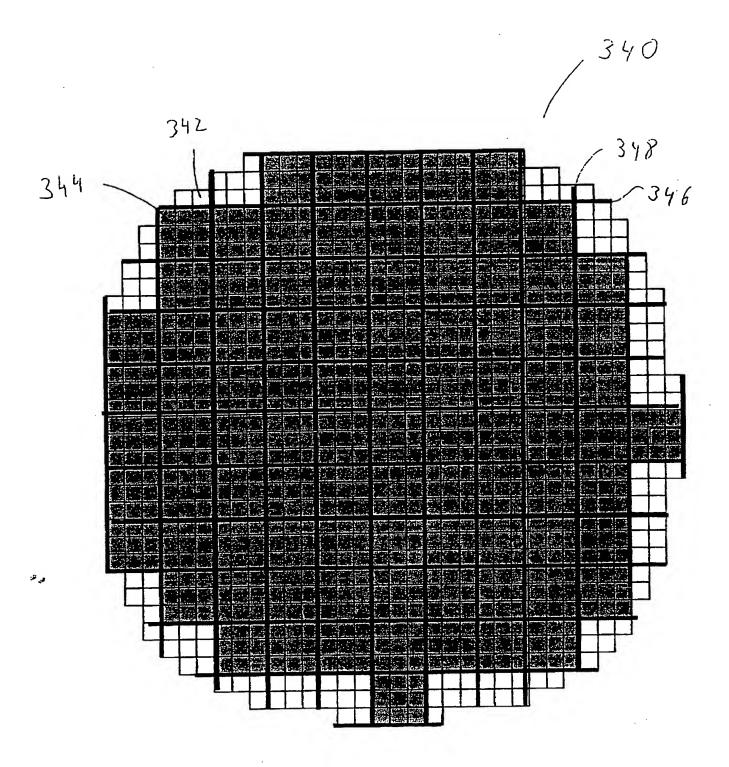


Fig 34

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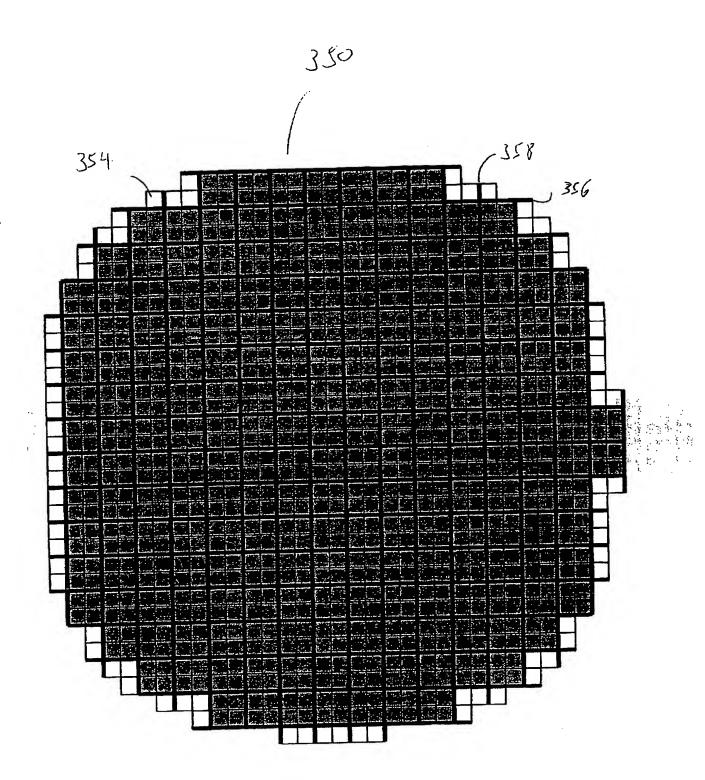
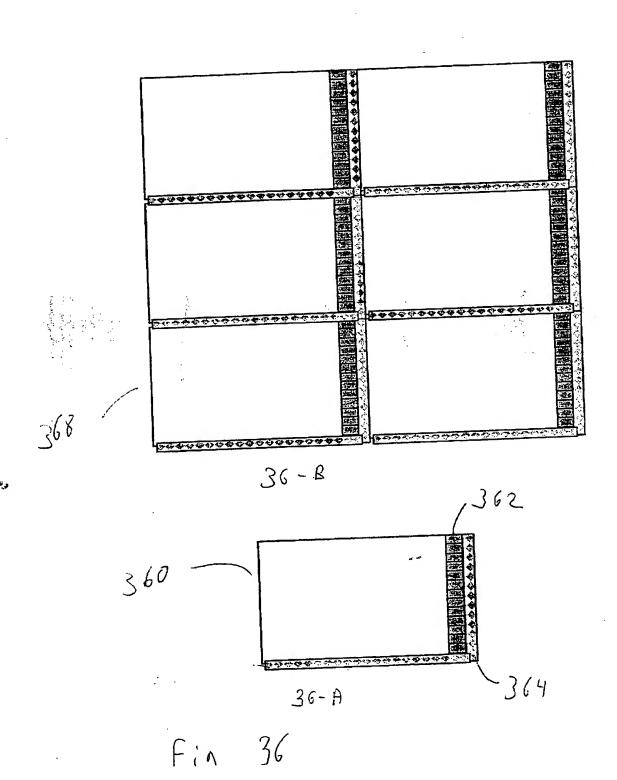
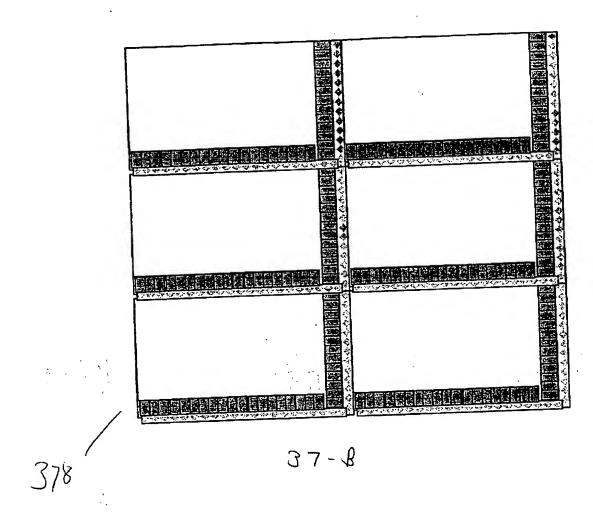


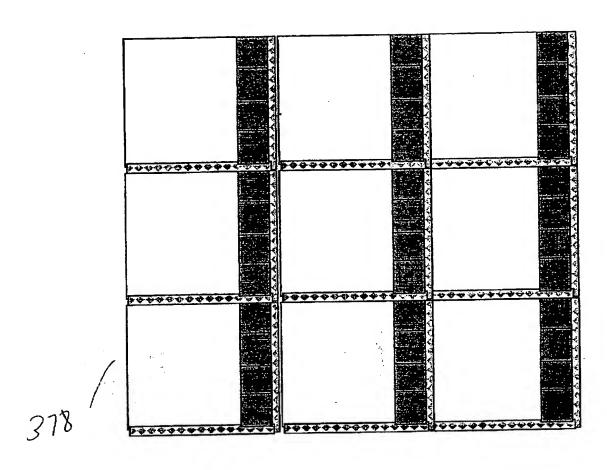
Fig 35





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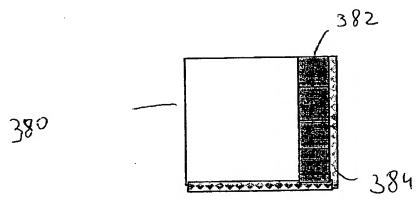
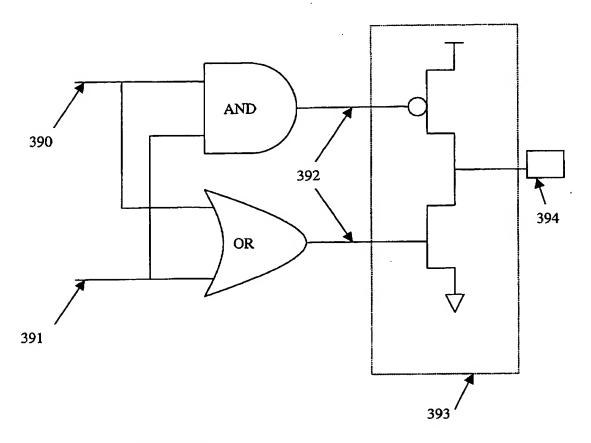


Fig 38



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Figure 39